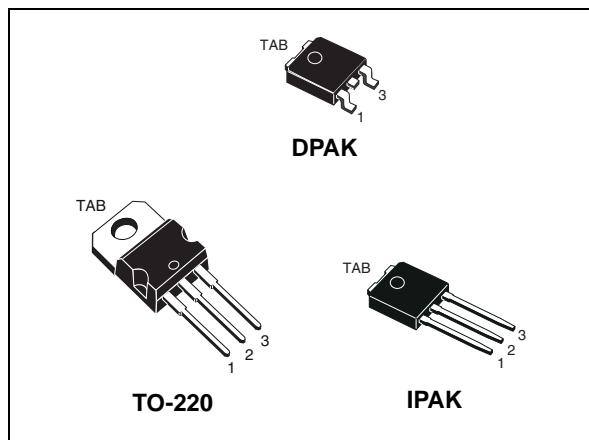


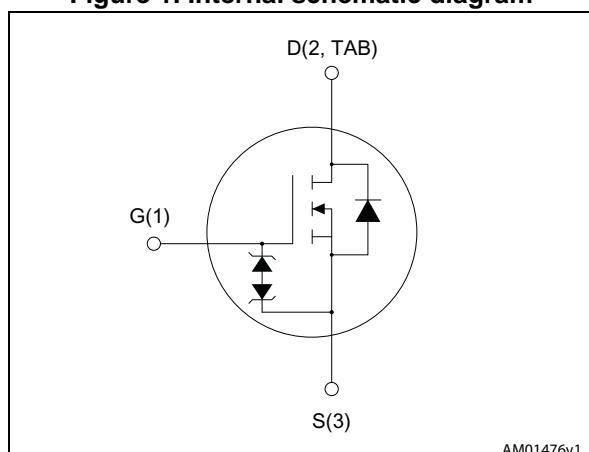
# STD2N105K5, STP2N105K5, STU2N105K5

N-channel 1050 V, 6  $\Omega$  typ., 1.5 A MDmesh™ K5  
Power MOSFETs in DPAK, TO-220 and IPAK packages

Datasheet - production data



**Figure 1. Internal schematic diagram**



## Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>	P <sub>TOT</sub>
STD2N105K5	1050 V	8 $\Omega$	1.5 A	60 W
STP2N105K5				
STU2N105K5				

- Industry's lowest R<sub>DS(on)</sub> x area
- Industry's best figure of merit (FoM)
- Ultra low gate charge
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications

## Description

These very high voltage N-channel Power MOSFETs are designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

**Table 1. Device summary**

Order codes	Marking	Package	Packaging
STD2N105K5	2N105K5	DPAK	Tape and reel
STP2N105K5		TO-220	Tube
STU2N105K5		IPAK	

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate- source voltage	$\pm 30$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	1.5	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	0.95	A
$I_{DM}^{(1)}$	Drain current (pulsed)	6	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	60	W
$I_{AR}$	Max current during repetitive or single pulse avalanche	0.5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D=0.5\text{ A}$ , $V_{DD}= 50\text{ V}$ )	90	mJ
$dv/dt^{(2)}$	Peak diode recovery voltage slope	4.5	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	V/ns
$T_j$ $T_{stg}$	Operating junction temperature Storage temperature	-55 to 150	$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 1.5\text{ A}$ ,  $di/dt \leq 100\text{ A}/\mu\text{s}$ ,  $V_{DS(\text{peak})} \leq V_{(\text{BR})DSS}$ .
3.  $V_{DS} \leq 840\text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	2.08	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.50	$^\circ\text{C/W}$

## 2 Electrical characteristics

(T<sub>case</sub> =25 °C unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0	1050			V
I <sub>DSS</sub>	Zero gate voltage, drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 1050 V			1	μA
		V <sub>DS</sub> = 1050 V, T <sub>C</sub> =125 °C			50	μA
I <sub>GSS</sub>	Gate-body leakage current	V <sub>GS</sub> = ± 20 V; V <sub>DS</sub> =0			±10	μA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 100 μA	3	4	5	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.75 A		6	8	Ω

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> =100 V, f=1 MHz, V <sub>GS</sub> =0	-	115	-	pF
C <sub>oss</sub>	Output capacitance		-	15	-	pF
C <sub>rss</sub>	Reverse transfer capacitance		-	0.5	-	pF
C <sub>o(tr)<sup>(1)</sup></sub>	Equivalent capacitance time related	V <sub>GS</sub> = 0, V <sub>DS</sub> = 0 to 840 V	-	17	-	pF
C <sub>o(er)<sup>(2)</sup></sub>	Equivalent capacitance energy related		-	6	-	pF
R <sub>G</sub>	Intrinsic gate resistance	f = 1 MHz open drain	-	20	-	Ω
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 840 V, I <sub>D</sub> = 1.5 A V <sub>GS</sub> =10 V (see <a href="#">Figure 18</a> )	-	10	-	nC
Q <sub>gs</sub>	Gate-source charge		-	1.5	-	nC
Q <sub>gd</sub>	Gate-drain charge		-	8	-	nC

1. Time related is defined as a constant equivalent capacitance giving the same charging time as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>
2. energy related is defined as a constant equivalent capacitance giving the same stored energy as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 525 \text{ V}, I_D = 0.75 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ <i>(see Figure 17)</i>	-	14.5	-	ns
$t_r$	Rise time		-	8.5	-	ns
$t_{d(off)}$	Turn-off-delay time		-	35	-	ns
$t_f$	Fall time		-	38.5	-	ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$I_{SD}$	Source-drain current		-		1.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		6	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 1.5 \text{ A}, V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 1.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	326		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ <i>(see Figure 19)</i>	-	1.19		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$V_{DD} = 60 \text{ V} T_J = 150^\circ\text{C}$ <i>(see Figure 19)</i>	-	7.3		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 1.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	525		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V} T_J = 150^\circ\text{C}$ <i>(see Figure 19)</i>	-	1.83		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$V_{DD} = 60 \text{ V} T_J = 150^\circ\text{C}$ <i>(see Figure 19)</i>	-	7		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

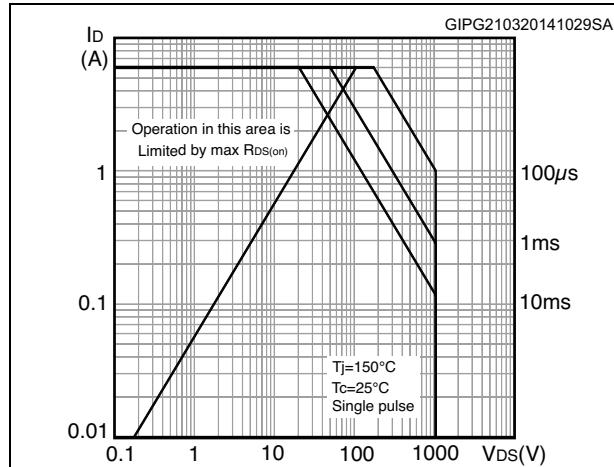
**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0$	30	-	-	V

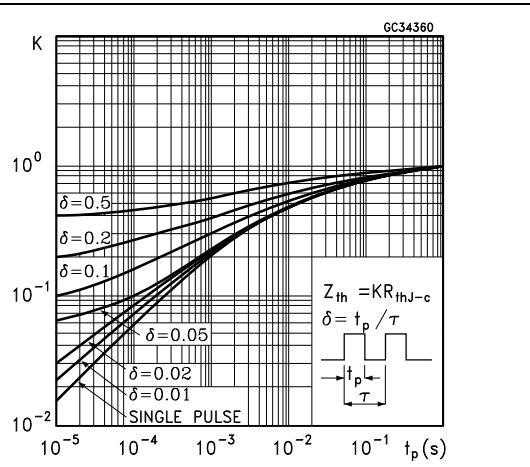
The built-in back-to-back Zener diodes have specifically been designed to enhance the device's ESD capability. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

## 2.1 Electrical characteristics (curves)

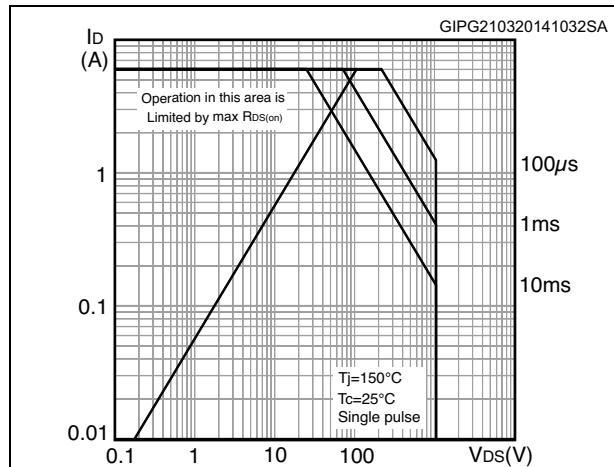
**Figure 2. Safe operating area for DPAK and IPAK**



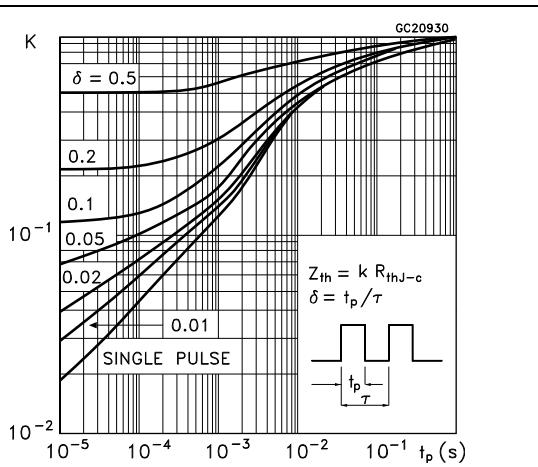
**Figure 3. Thermal impedance for DPAK and IPAK**



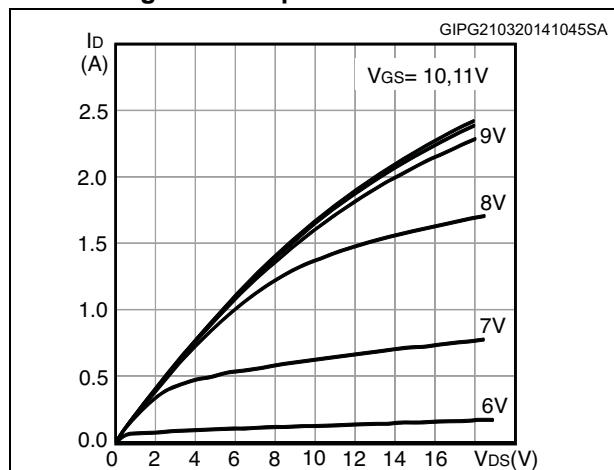
**Figure 4. Safe operating area for TO-220**



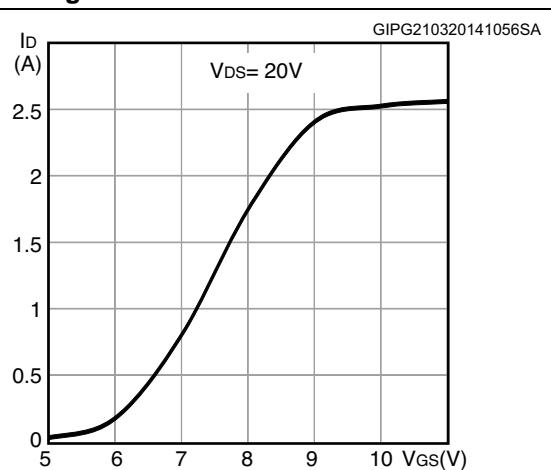
**Figure 5. Thermal impedance for TO-220**

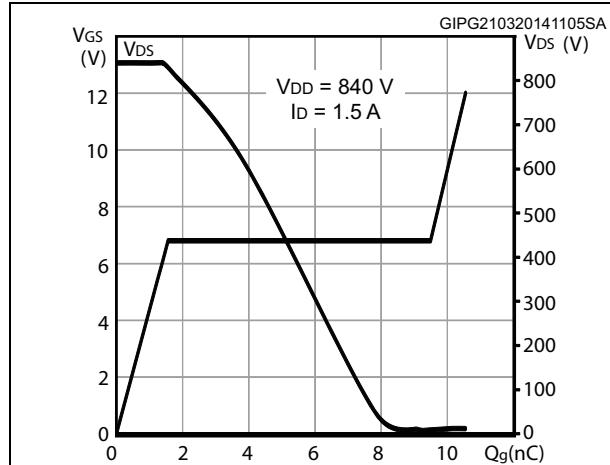
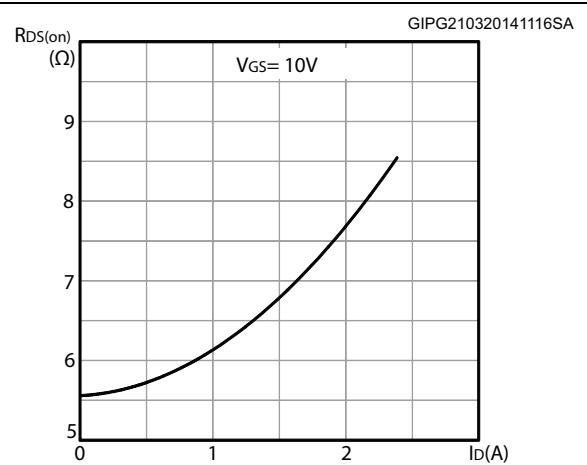
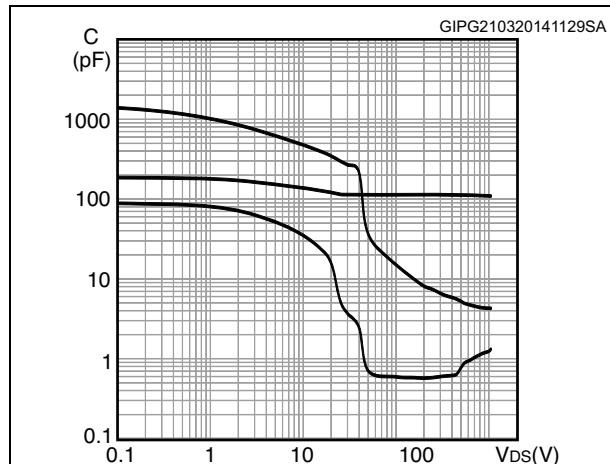
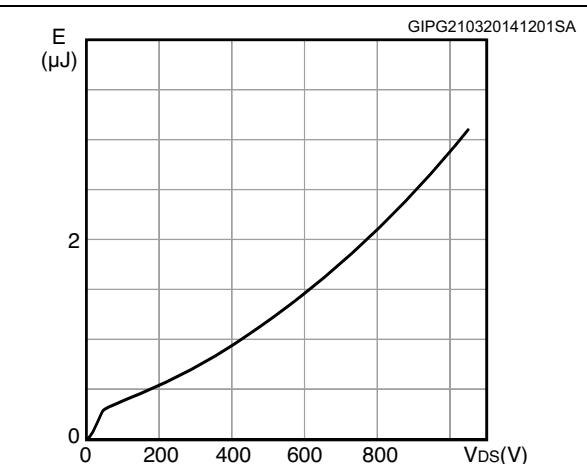
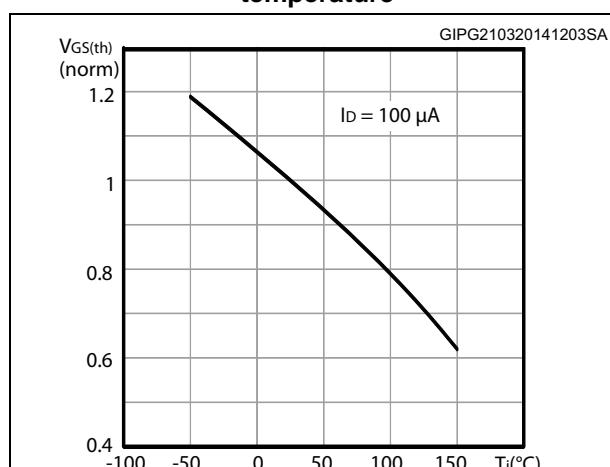
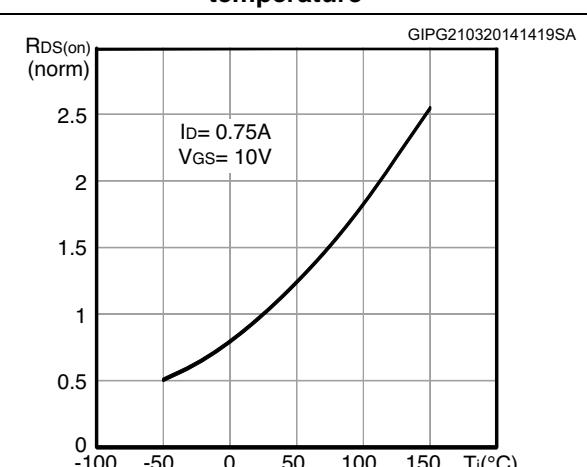


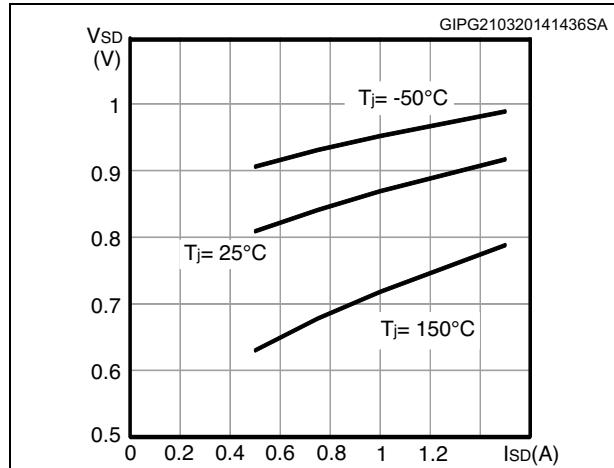
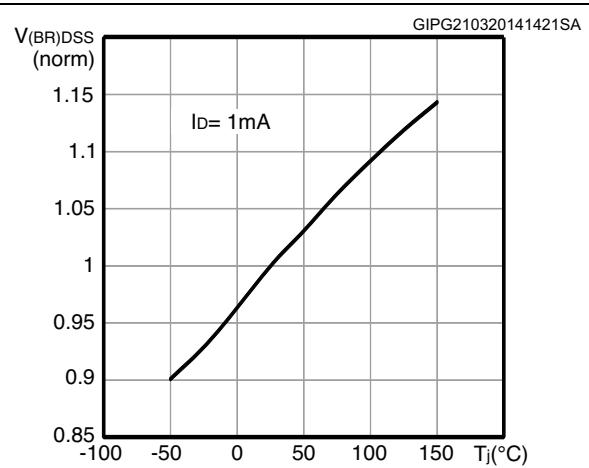
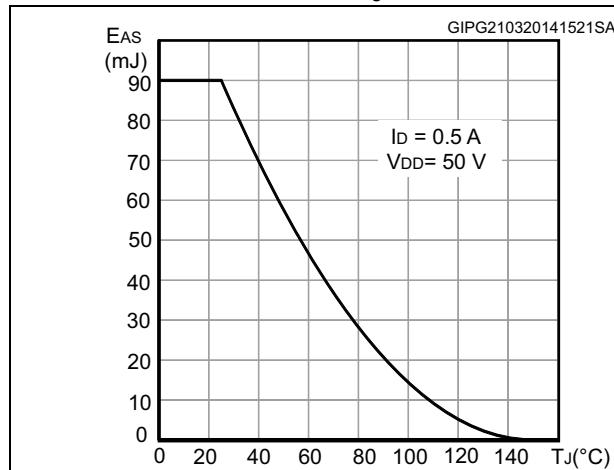
**Figure 6. Output characteristics**



**Figure 7. Transfer characteristics**

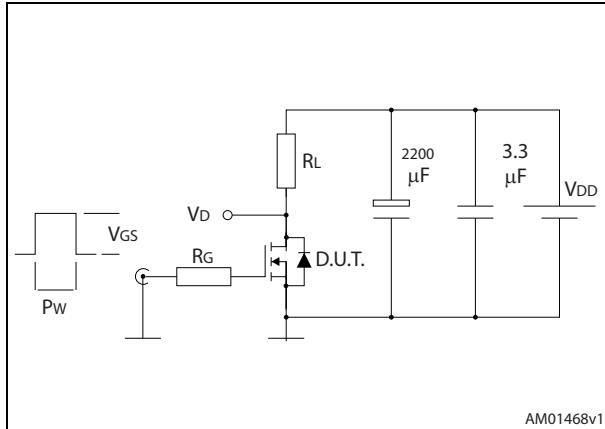


**Figure 8. Gate charge vs gate-source voltage****Figure 9. Static drain-source on-resistance****Figure 10. Capacitance variations****Figure 11. Output capacitance stored energy****Figure 12. Normalized gate threshold voltage vs temperature****Figure 13. Normalized on-resistance vs temperature**

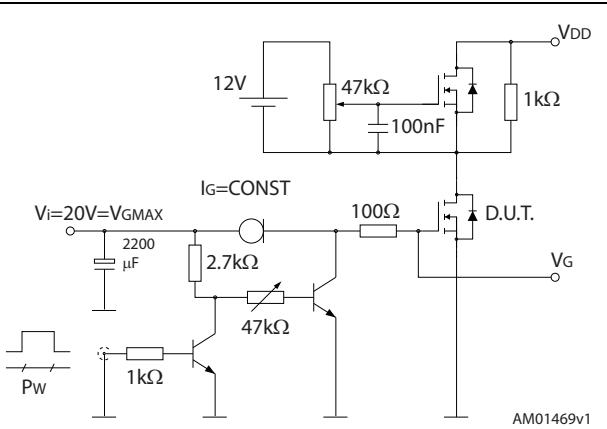
**Figure 14. Source-drain diode forward characteristics****Figure 15. Normalized  $V_{(BR)DSS}$  vs temperature****Figure 16. Maximum avalanche energy vs starting  $T_J$** 

### 3 Test circuits

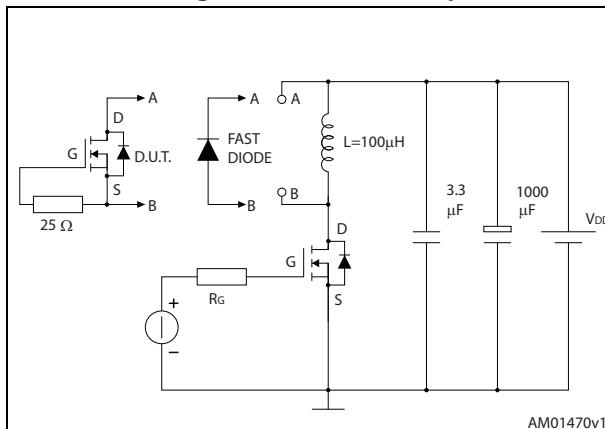
**Figure 17. Switching times test circuit for resistive load**



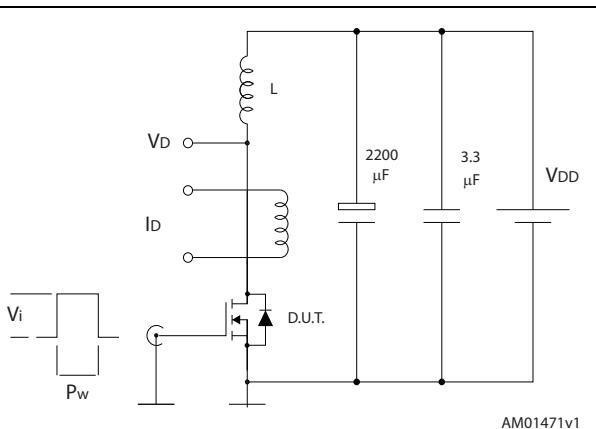
**Figure 18. Gate charge test circuit**



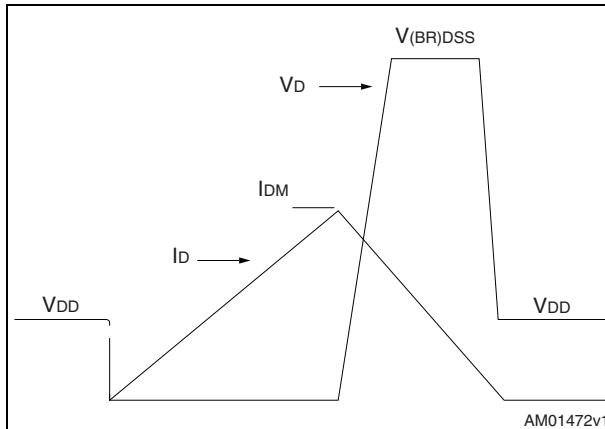
**Figure 19. Test circuit for inductive load switching and diode recovery times**



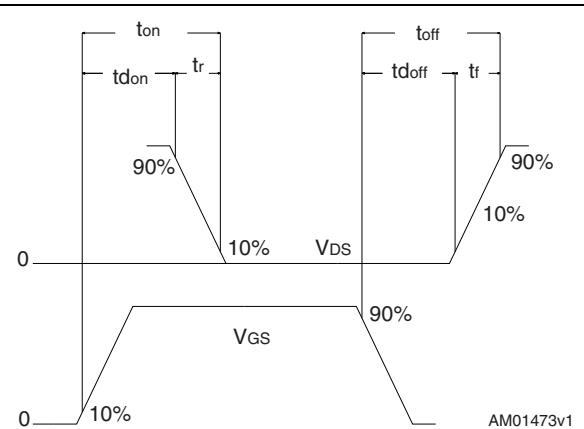
**Figure 20. Unclamped inductive load test circuit**



**Figure 21. Unclamped inductive waveform**



**Figure 22. Switching time waveform**

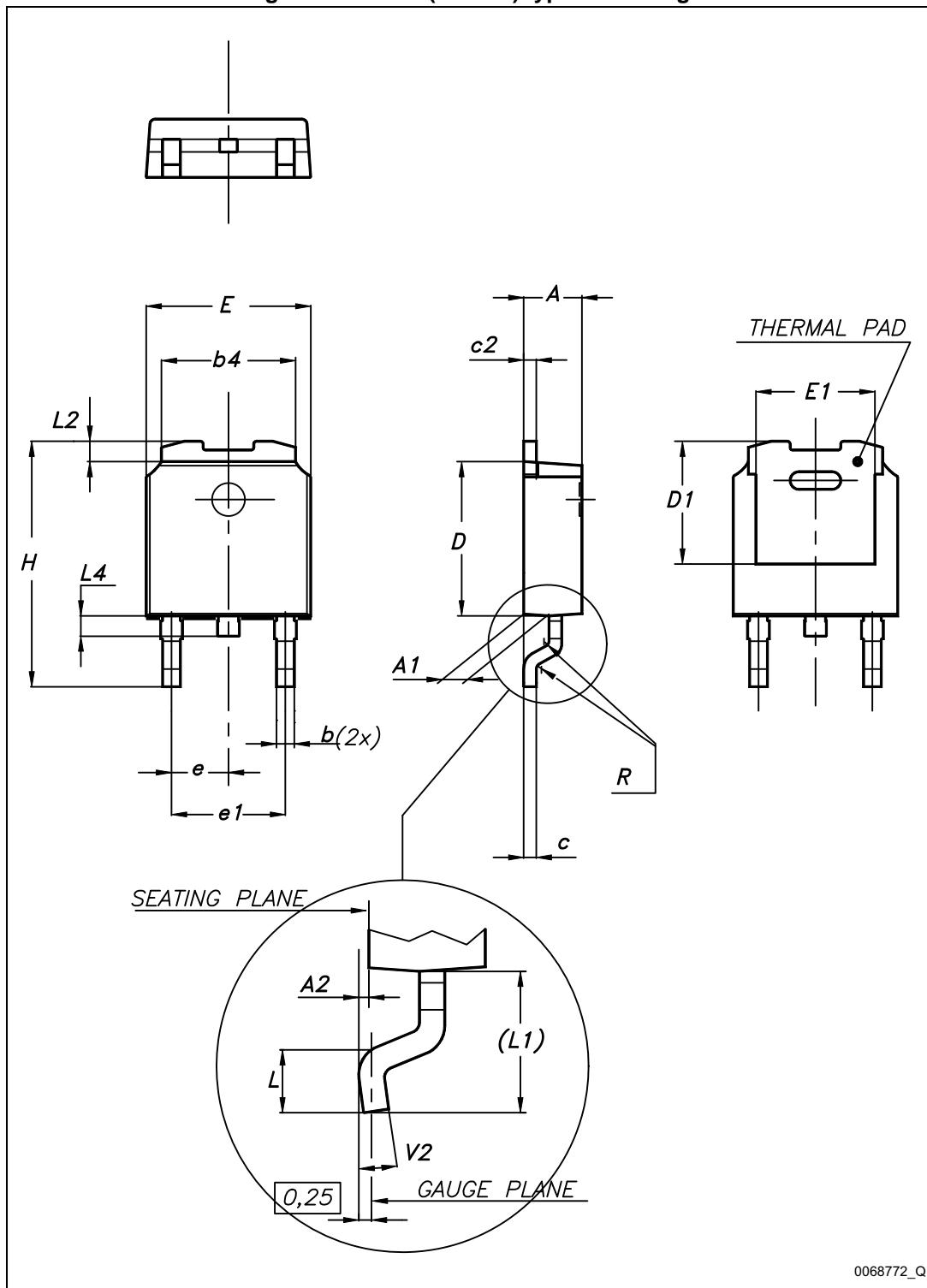


## 4 Package mechanical data

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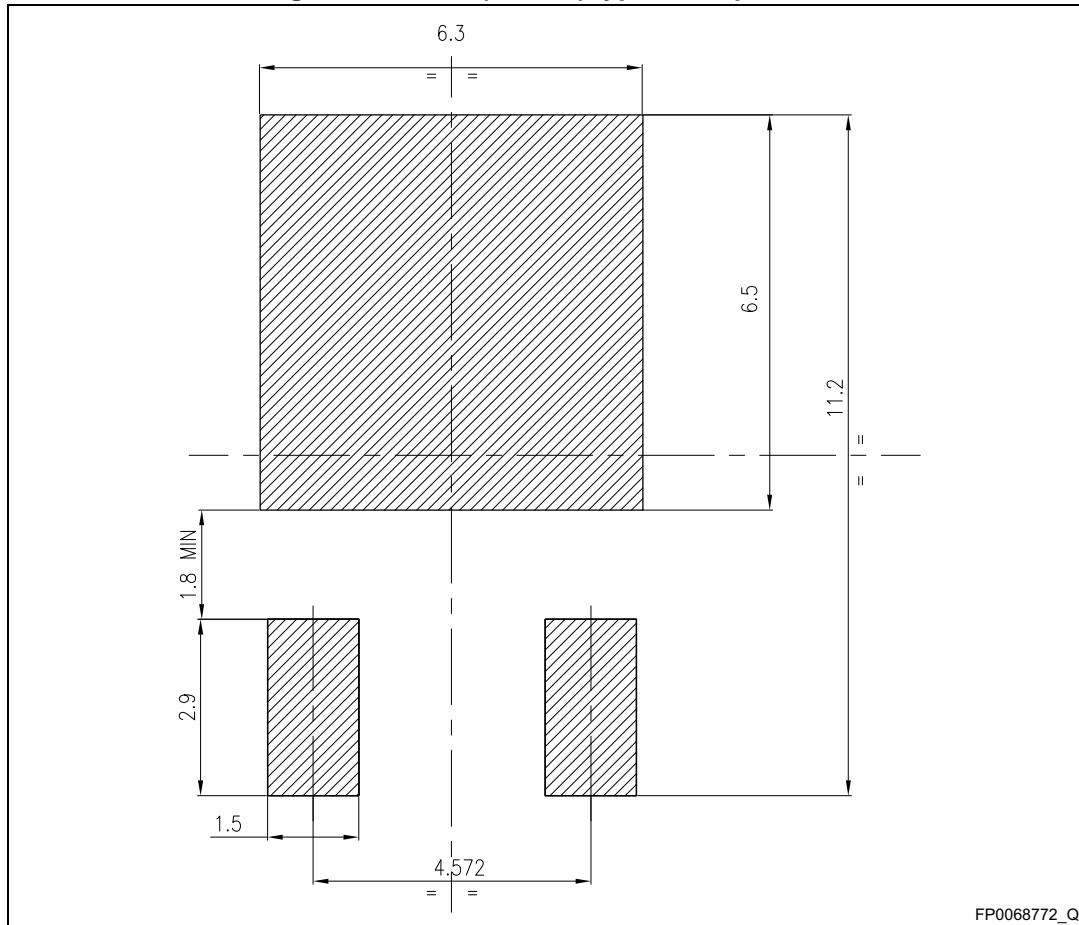
## 4.1 DPAK, STD2N105K5

Figure 23. DPAK (TO-252) type A drawing



**Table 9. DPAK (TO-252) type A mechanical data**

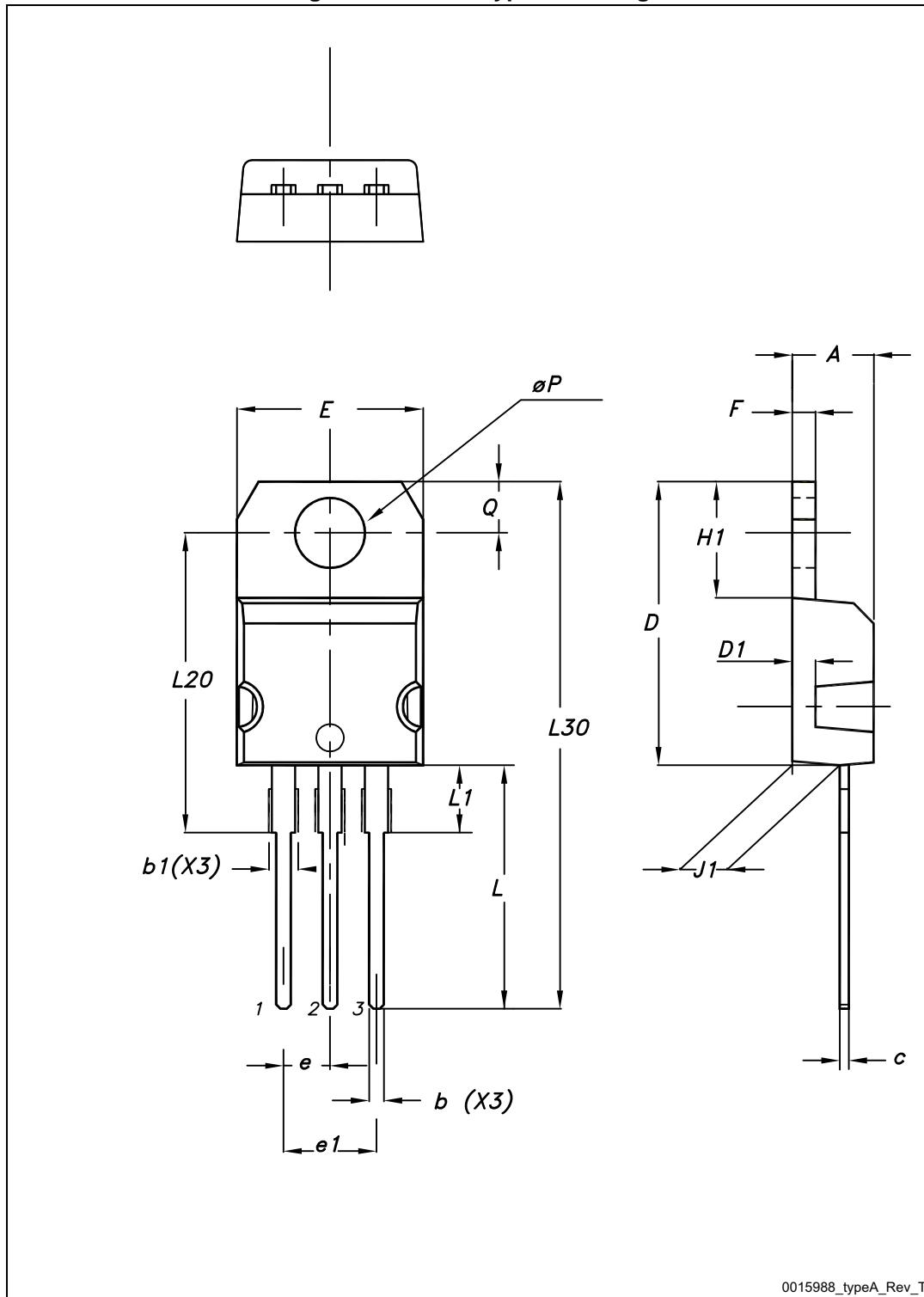
Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
L1		2.80	
L2		0.80	
L4	0.60		1.00
R		0.20	
V2	0°		8°

**Figure 24. DPAK (TO-252) type A footprint (a)**

a. All dimensions are in millimeters

## 4.2 TO-220, STP2N105K5

**Figure 25. TO-220 type A drawing**

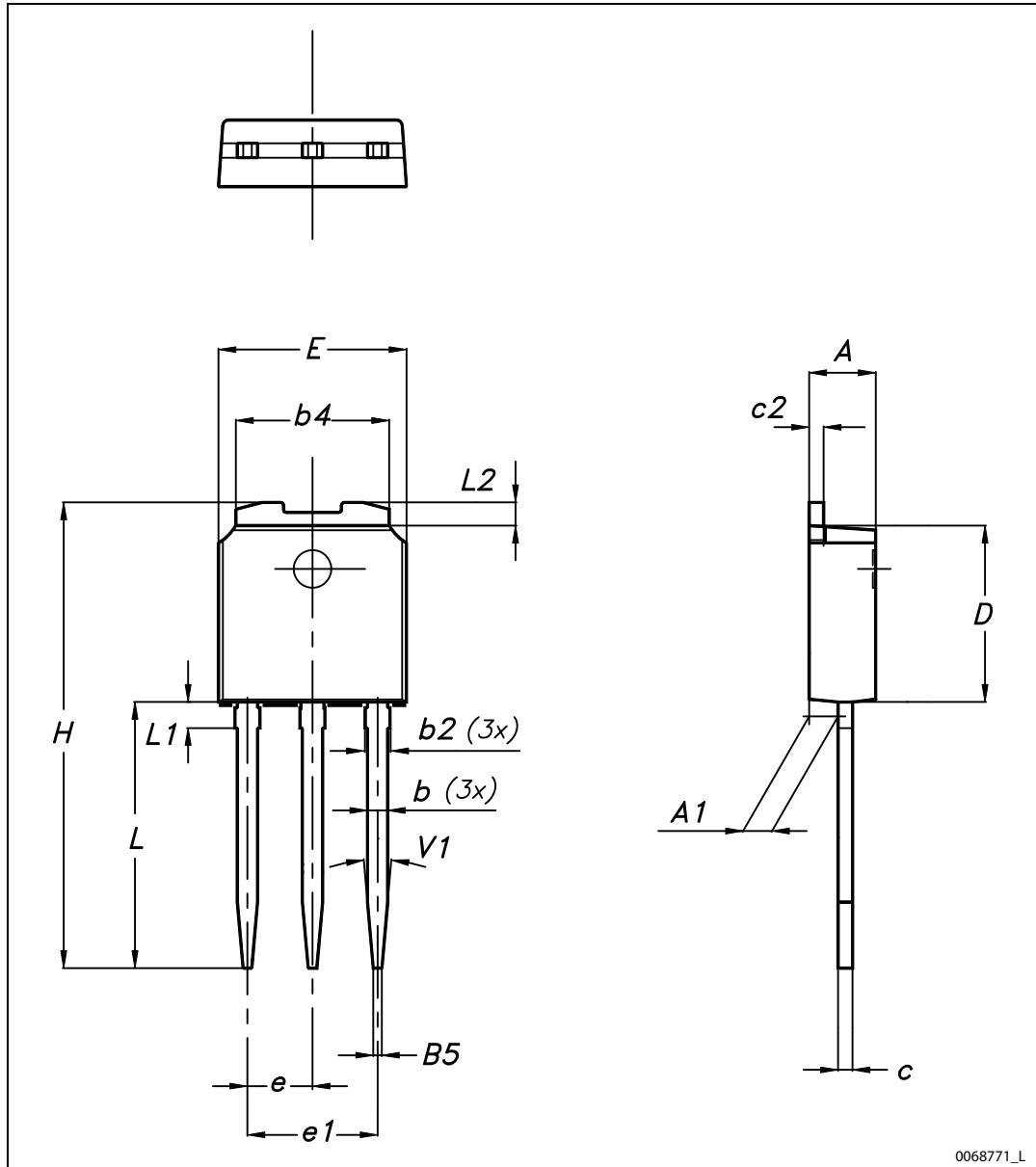


**Table 10. TO-220 type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

### 4.3 IPAK, STU2N105K5

Figure 26. IPAK (TO-251) drawing



**Table 11. IPAK (TO-251) type A mechanical data**

DIM	mm.		
	min.	typ.	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

## 5 Packaging mechanical data

Figure 27. Tape

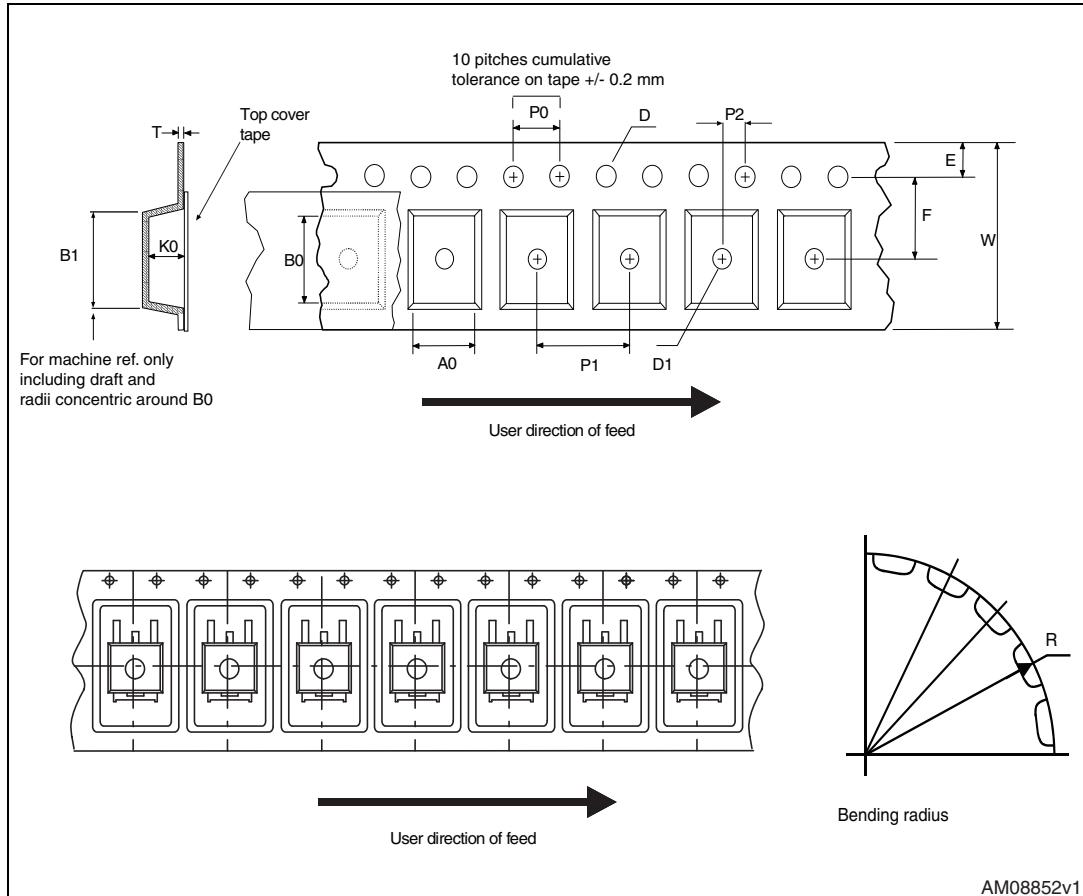


Figure 28. Reel

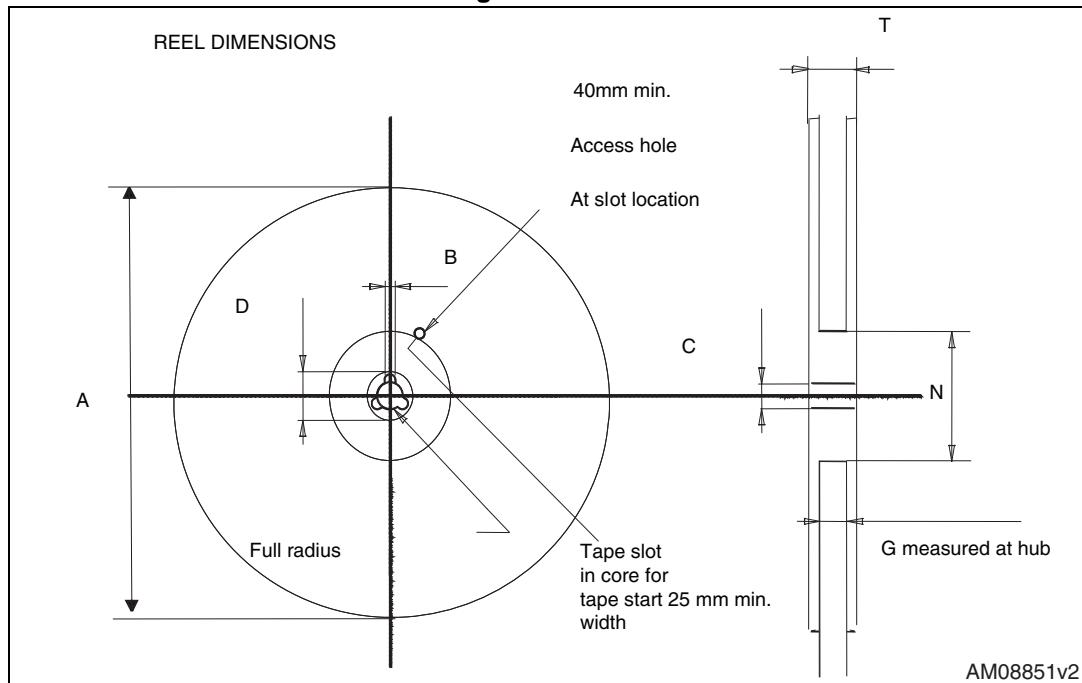


Table 12. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## 6 Revision history

Table 13. Document revision history

Date	Revision	Changes
08-May-2014	1	First release.
14-Nov-2014	2	Document status promoted from preliminary to production data. Updated title, features and description in cover page. Updated <i>Figure 9: Static drain-source on-resistance, Section 4.1: DPAK, STD2N105K5</i> and <i>Section 4.3: IPAK, STU2N105K5</i> . Minor text changes.
19-Nov-2004	3	Updated $V_{GS}$ in <i>Table 2: Absolute maximum ratings</i> and $I_{GSS}$ in <i>Table 4: On /off states</i> .

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